

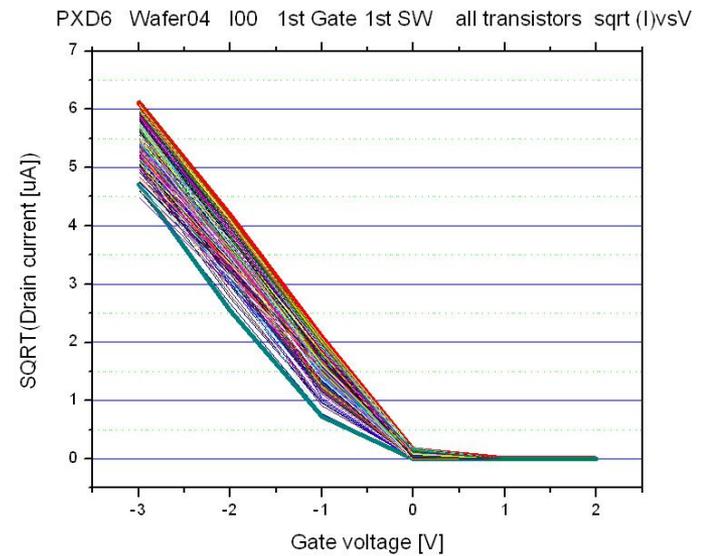
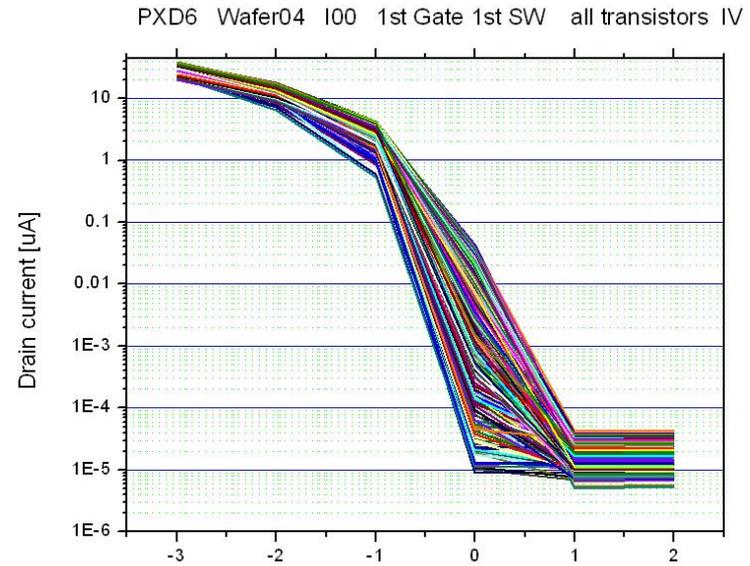
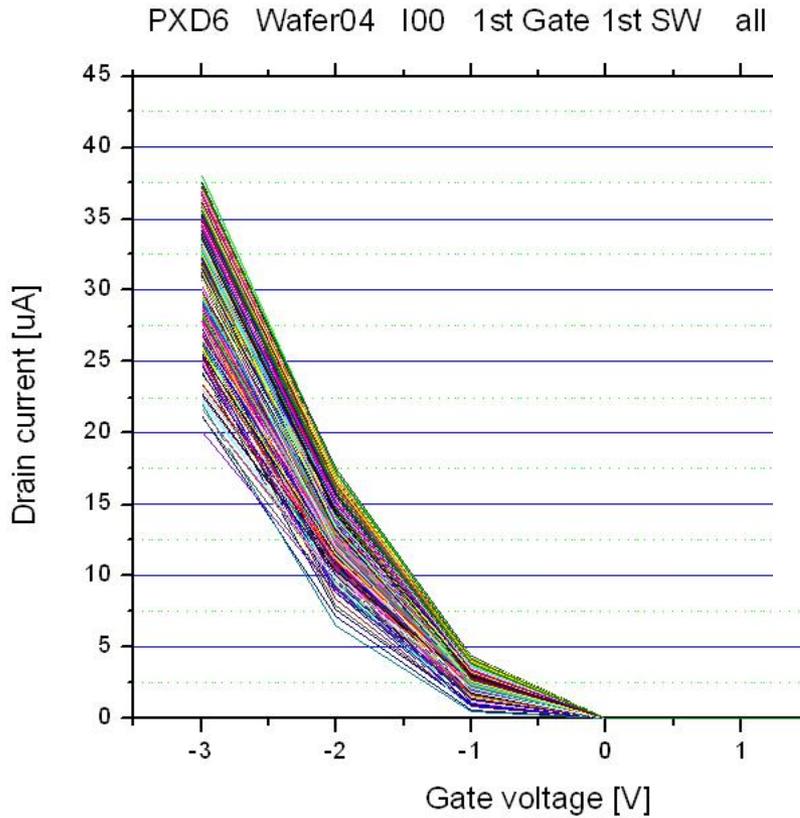
Belle2- ASIC Review July 2015

Pedestal spread (sensors)

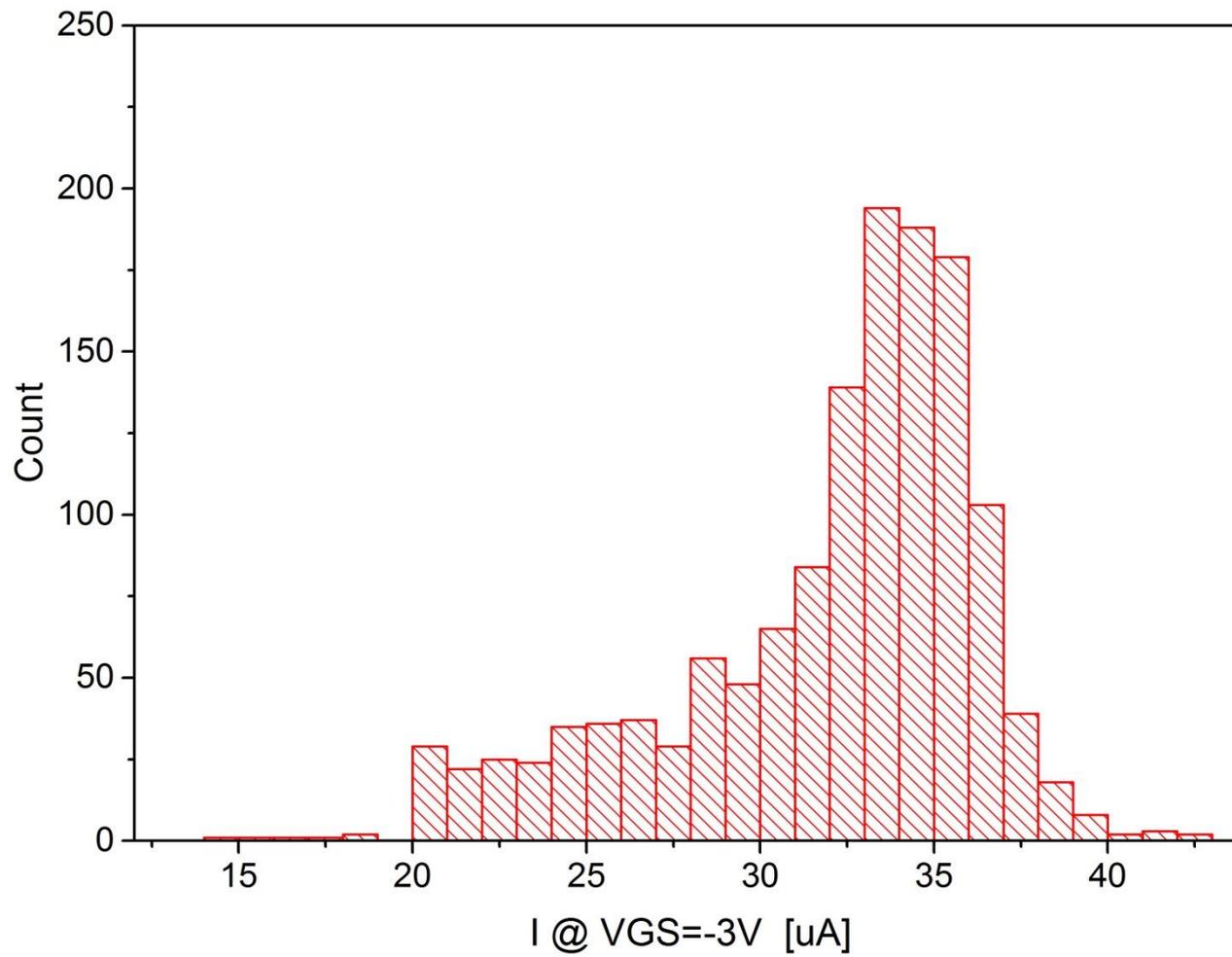
Preparation

PXD6 results

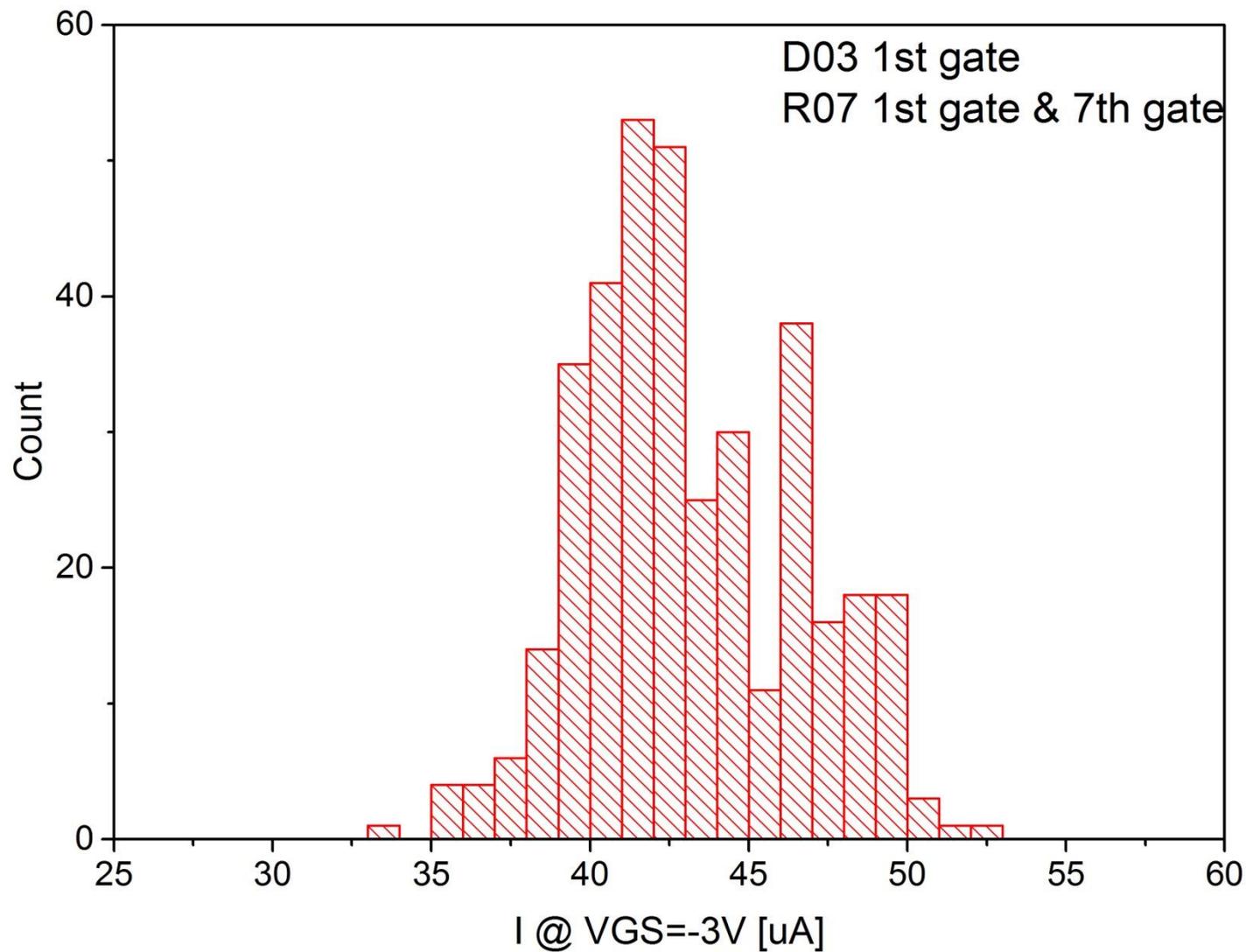
768 Depfets – Big Matrix I00 first row



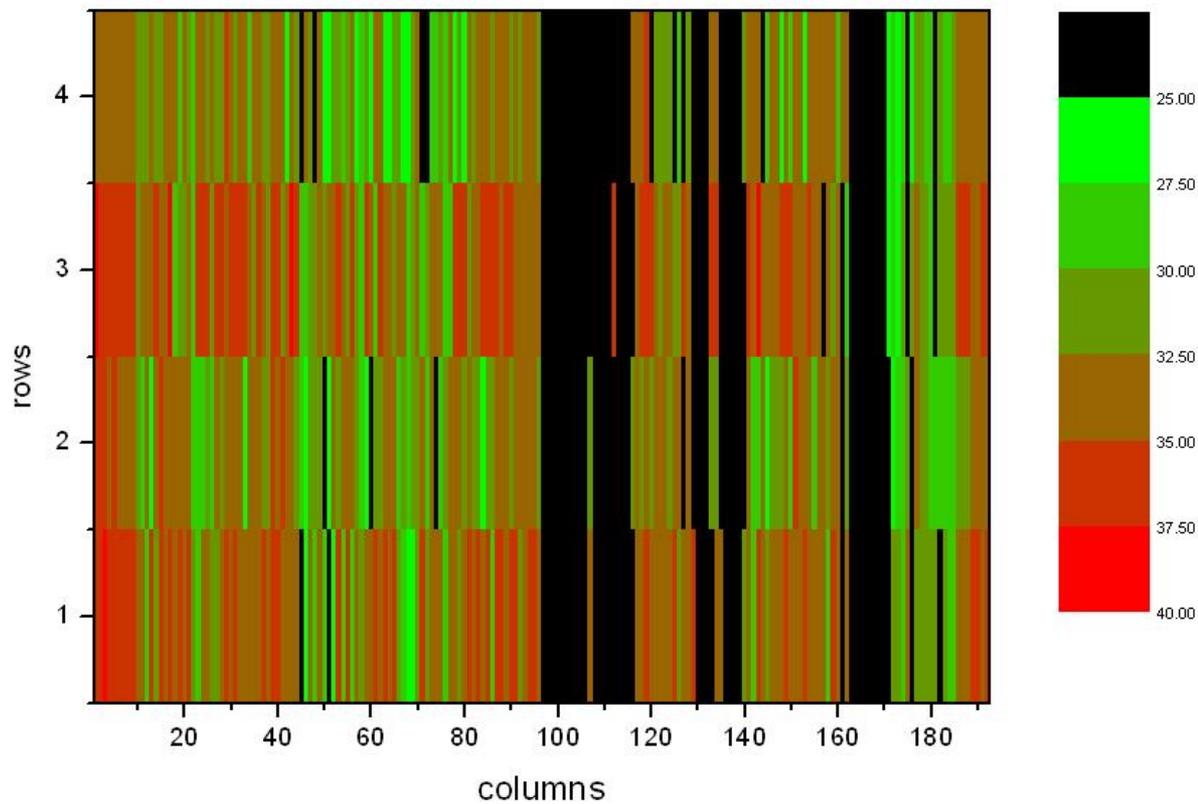
W04 I00 3 gates at different SW 1,2 and 4



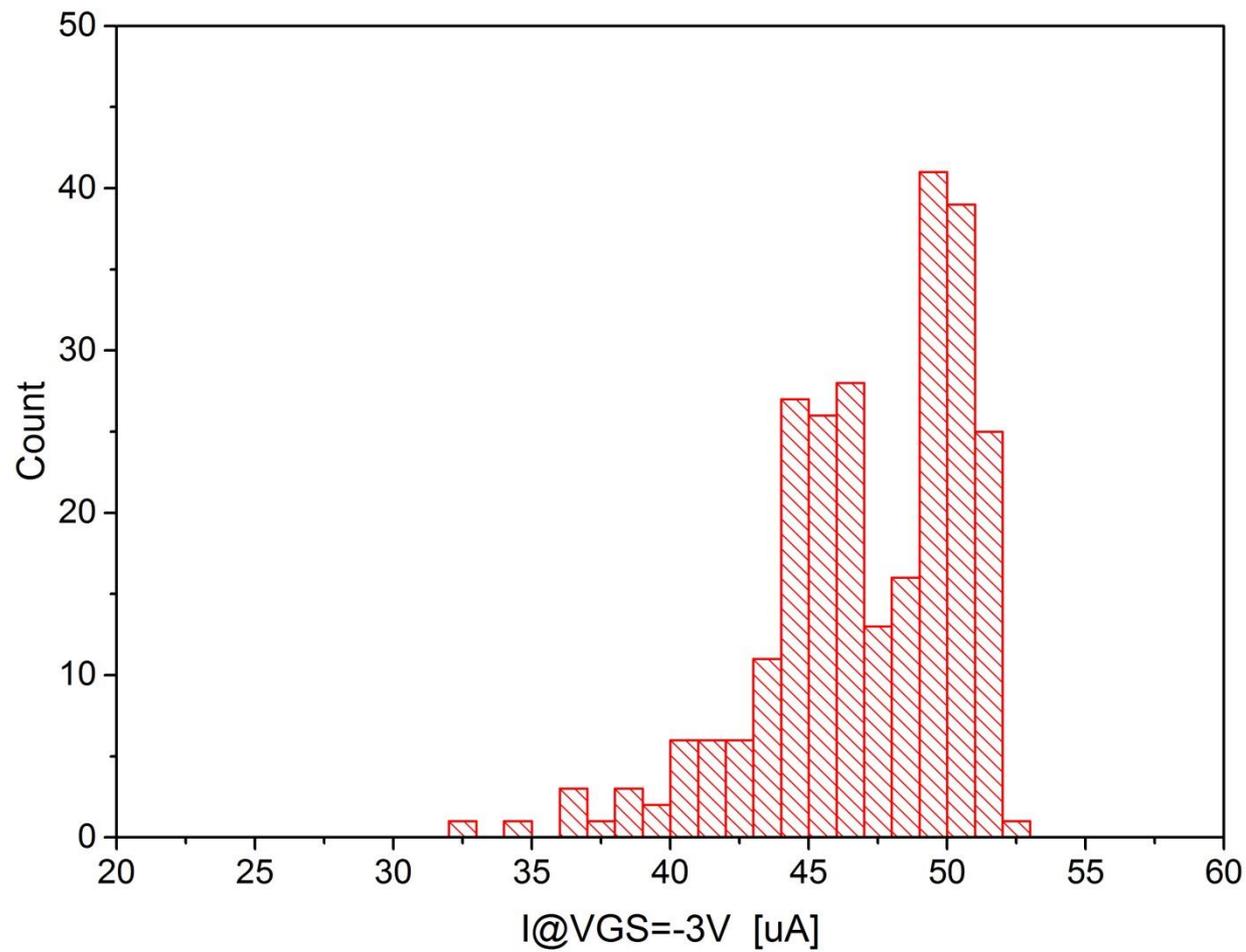
W04 3 gate raws on different positions on wafer



PXD6 Wafer 04 I00 1Gate 1 SW Id @ Vgs= -3V [μ A]



W04 _ ST_SD_SCG_Z075_T1



● Possible reasons for pedestal variations



- A) Parasitic Source resistors (gap between Source implant and active channel)
(repaired in PXD9: see last Seeon talk)

- B) Gate length (**litho, etching**)

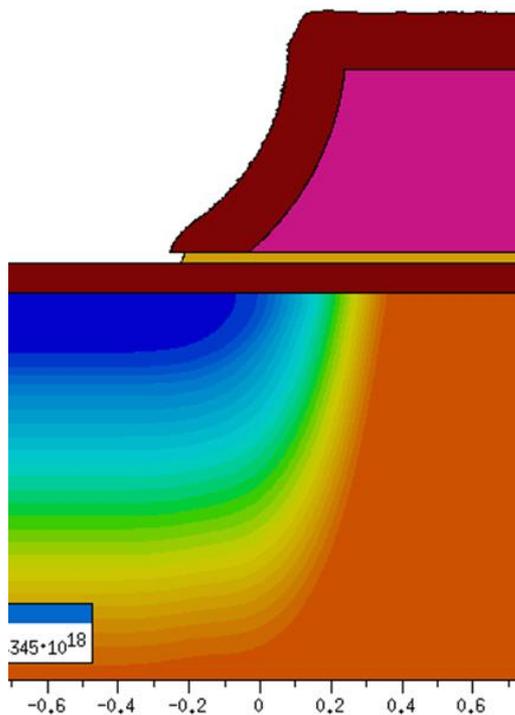
- B) Threshold voltage (**implantation**, gate oxide thickness, V_{fb})

- C) **Bad channels** (poly etch relicts during implantations)

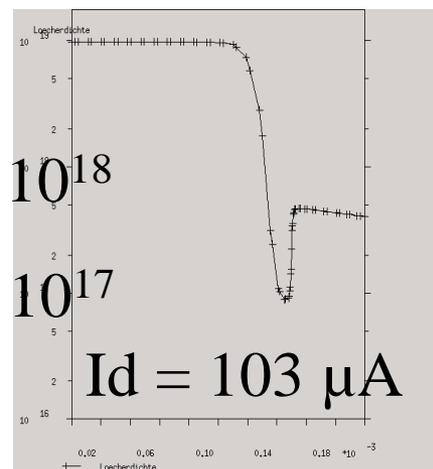
● A) Parasitic Source resistor

$$V_G = -3V, V_D = -3V$$

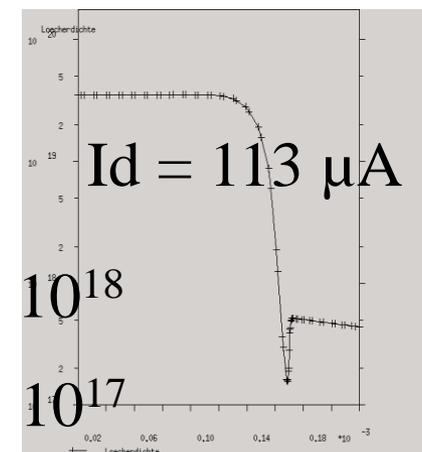
Implant before oxidation



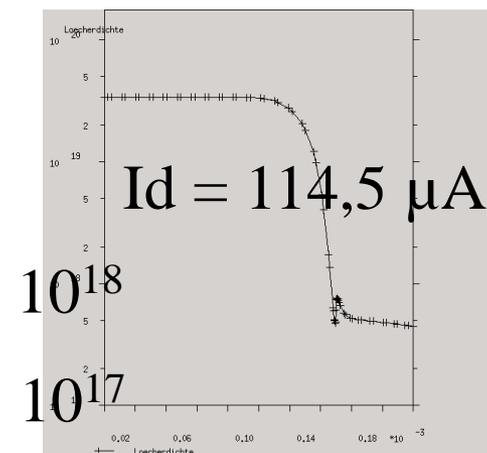
after Ox.



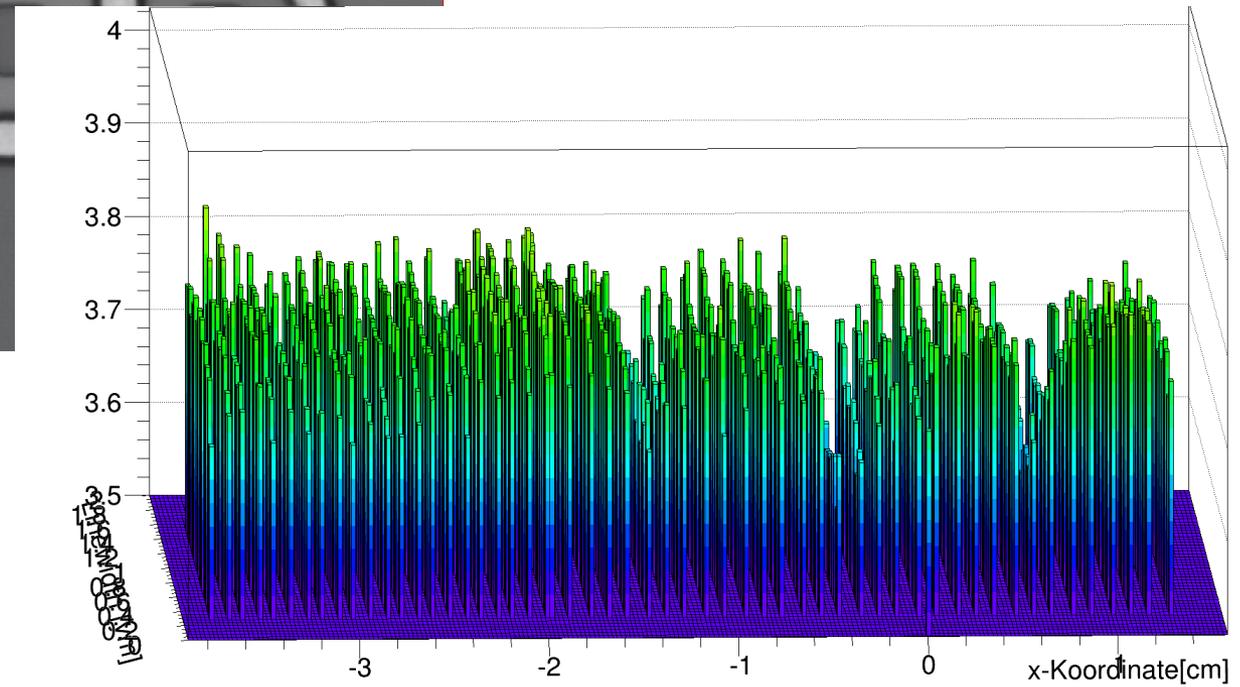
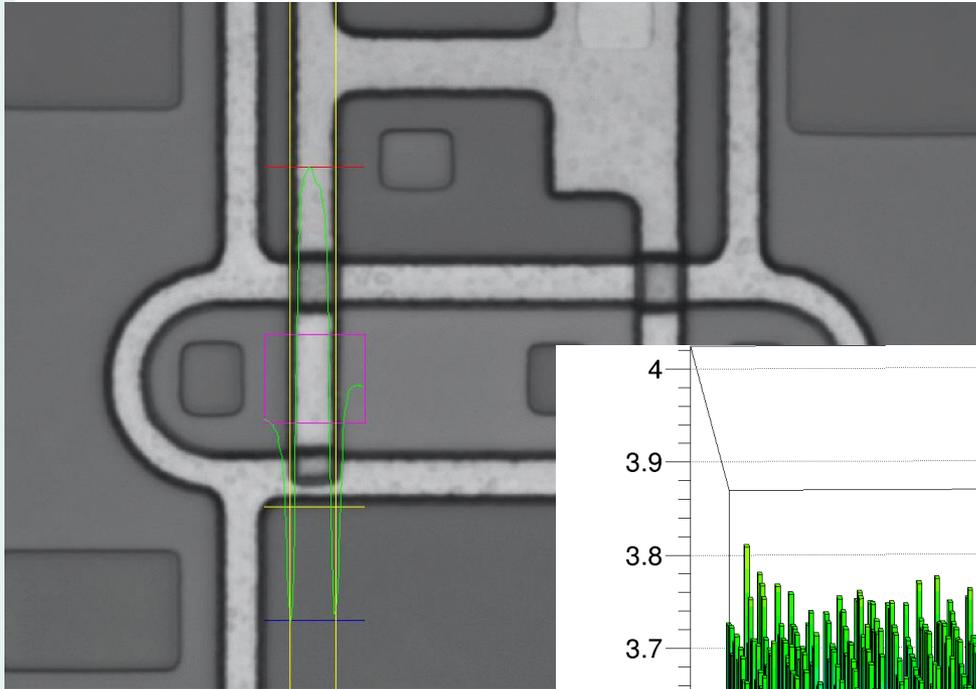
before Ox.

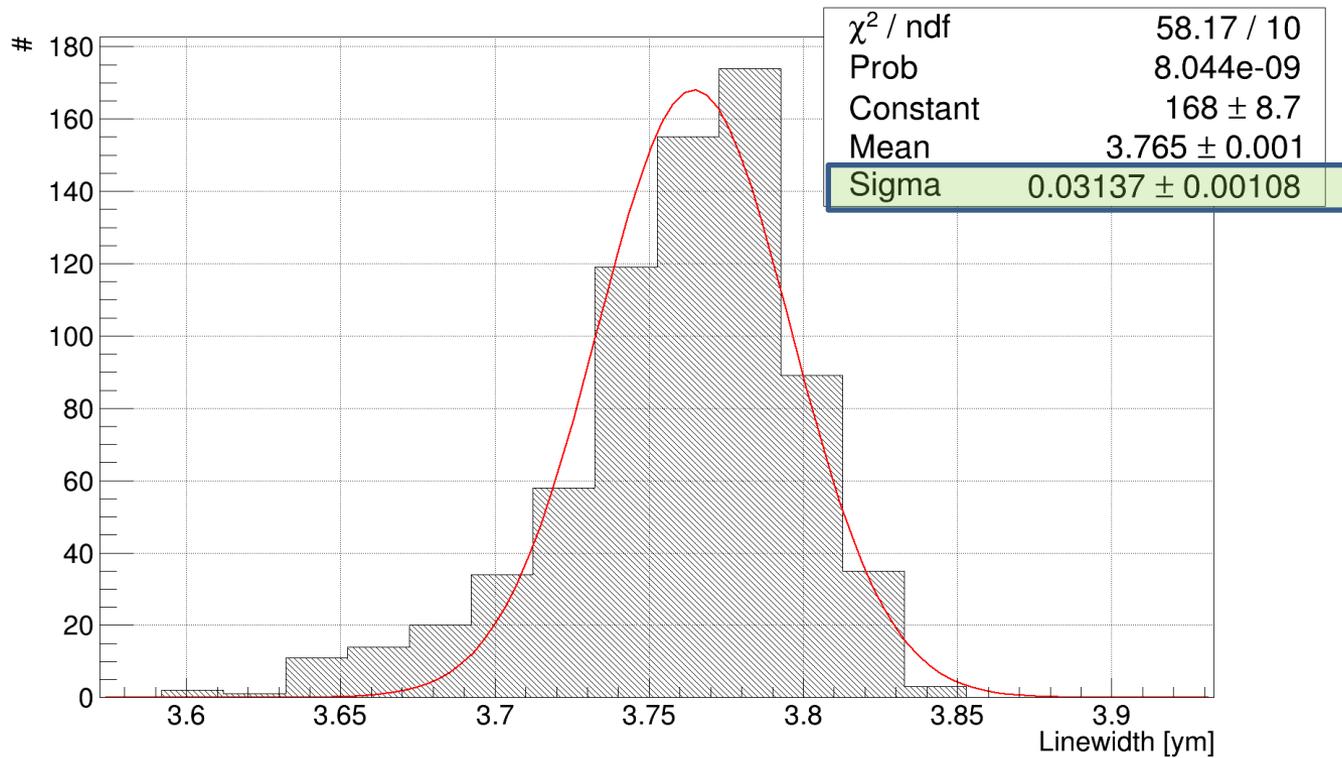


before oxidation
+ optimized
implantation
parameter

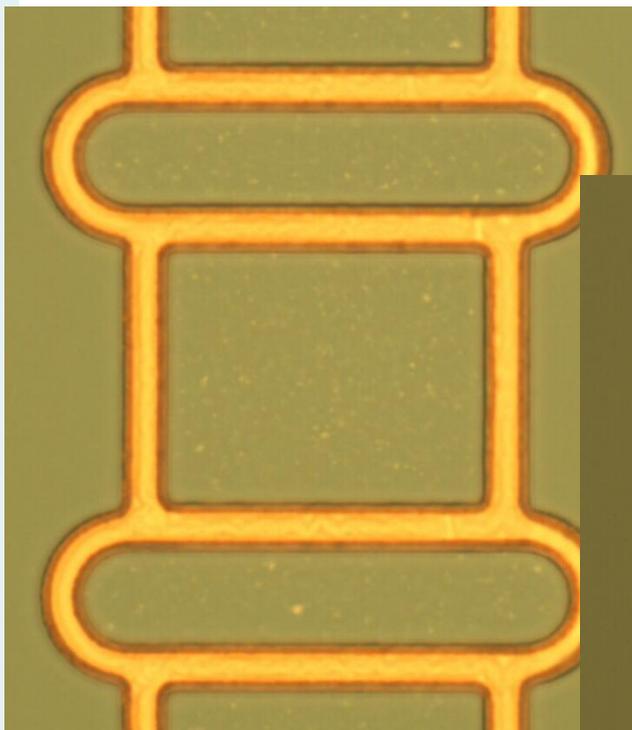


● B) Gate length variation – measured at PXD9-3 Wafer 28



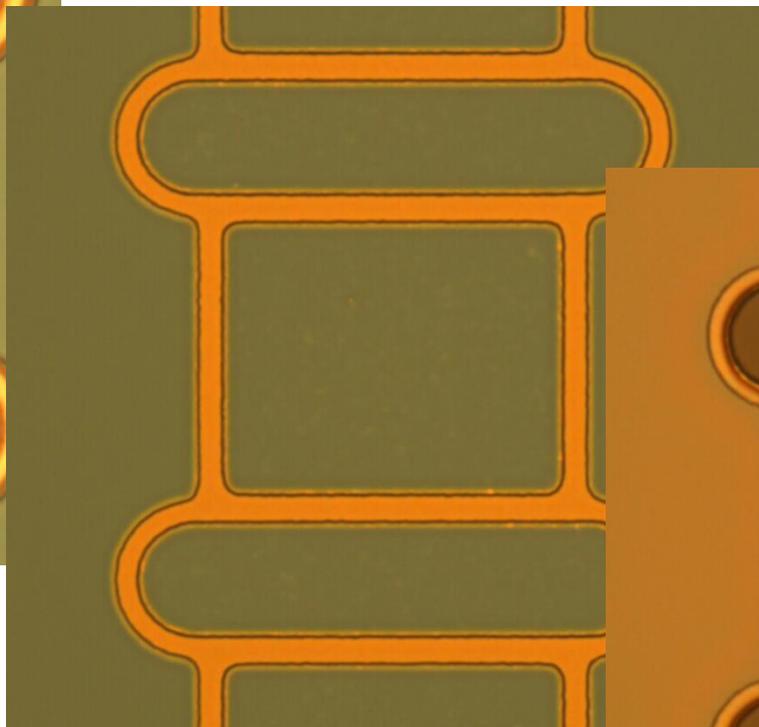


● C) Bad Channels: Implantation through poly etch relights



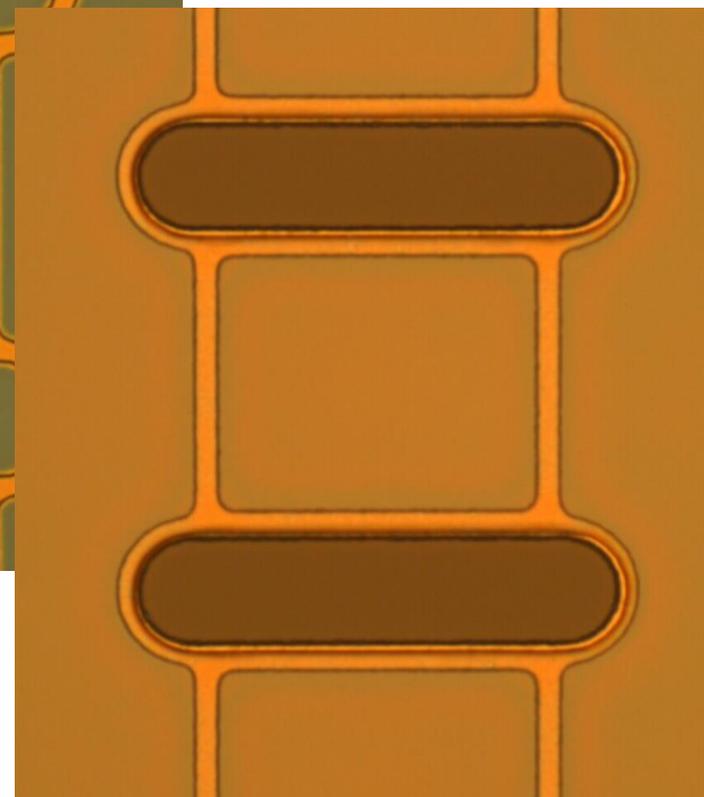
Shallow p implant
(PXD6)

After etching



Shallow p implant
(PXD9)

After removal



After nitride etch

● D) Implantation dose variations



In the DEPFET channel:

2 subtracting doses: Internal Gate + shallow p (threshold adjustment)
in the range of 10^{12}cm^{-2}

Implanter specification: $< 0.5\%$ (rms), measured 0.3%

$2 \times 0.5\% = 1\%$ corresponds to 10^{10}cm^{-2} dose variation

PXD9:

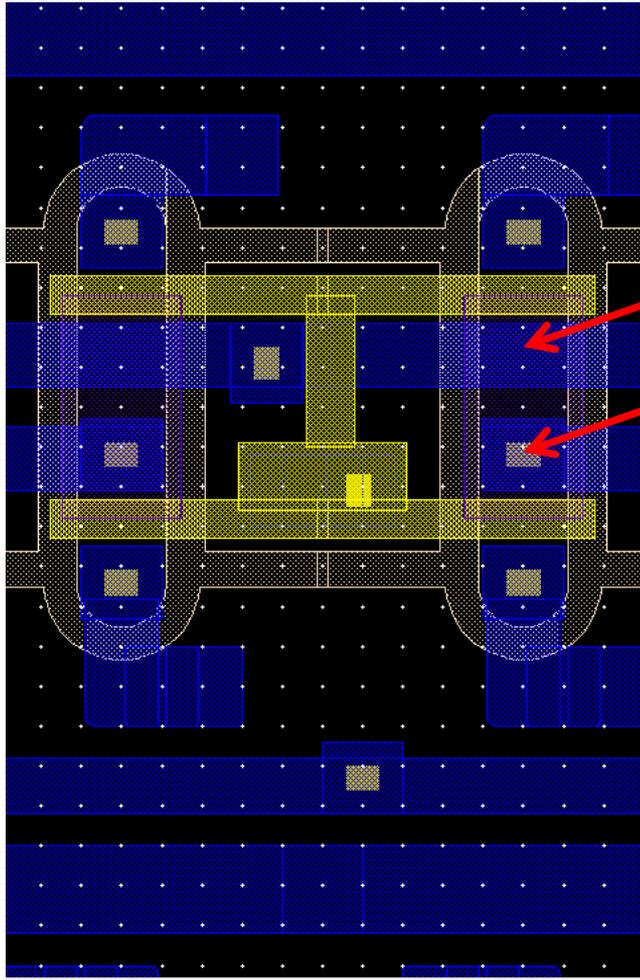
-> thresh. variation 40mV -> $3\mu\text{A}$ @ $g_m=75\mu\text{S}$ ($V_{gs}=-3\text{V}$)



Drain currents PXD9 - W35 (22000,12000 pixel)



$V_G = -3V, V_{DS} = -5V$ $V_{AC} = 15V, V_{CG} = 5V$	Average current [- μ A]		pedestal spread [μ A] (2σ)		Threshold voltage [V]	
	OF1	OF2	OF1	OF2	OF1	OF2
switcher1 gaterow1	121	114	21 (7)	17 (6)	0,051	-0,016
switcher1 gaterow2	119	113	16 (6)	17 (5)	0,039	-0,020
switcher2 gaterow1	127	122	20 (8)	23 (9)	0,093	0,055
switcher2 gaterow2	126	123	22 (8)	24 (9)	0,098	0,061
switcher2 gaterow3	124	-	13 (5)	-	0,081	-
switcher2 gaterow4	123	-	15 (6)	-	0,073	-
switcher3 gaterow1	119	123	15 (5)	18 (6)	0,025	0,059
switcher3 gaterow2	120	123	17 (5)	16 (5)	0,029	0,057
switcher3 gaterow3	120	-	16 (6)	-	0,026	-
switcher3 gaterow4	121	-	17 (6)	-	0,054	-
switcher4 gaterow1	125	124	19 (7)	25 (10)	0,102	0,081
switcher4 gaterow2	124	124	15 (5)	16 (5)	0,095	0,085
switcher4 gaterow3	124	-	13 (5)	-	0,093	-
switcher4 gaterow4	125	-	15 (6)	-	0,102	-
switcher5 gaterow1	122	120	19 (7)	23 (7)	0,090	0,097
switcher5 gaterow2	122	120	14 (5)	14 (5)	0,087	0,061
switcher5 gaterow3	123	-	16 (5)	-	0,109	-
switcher5 gaterow4	121	-	17 (6)	-	0,090	-
switcher6 gaterow1	122	120	15 (5)	19 (6)	0,074	0,055
switcher6 gaterow2	120	120	17 (6)	15 (5)	0,058	0,050
switcher6 gaterow3	122	-	15 (6)	-	0,076	-
switcher6 gaterow4	121	-	17 (6)	-	0,067	-
Total average	122,3	120,50	16,5 (6,0)	18,9 (6,5)	0,073	0,052



Yield lesson from PXD6:
Relaxing the topology

Clear line must run parallel to
Source
-> asymmetric Source contact

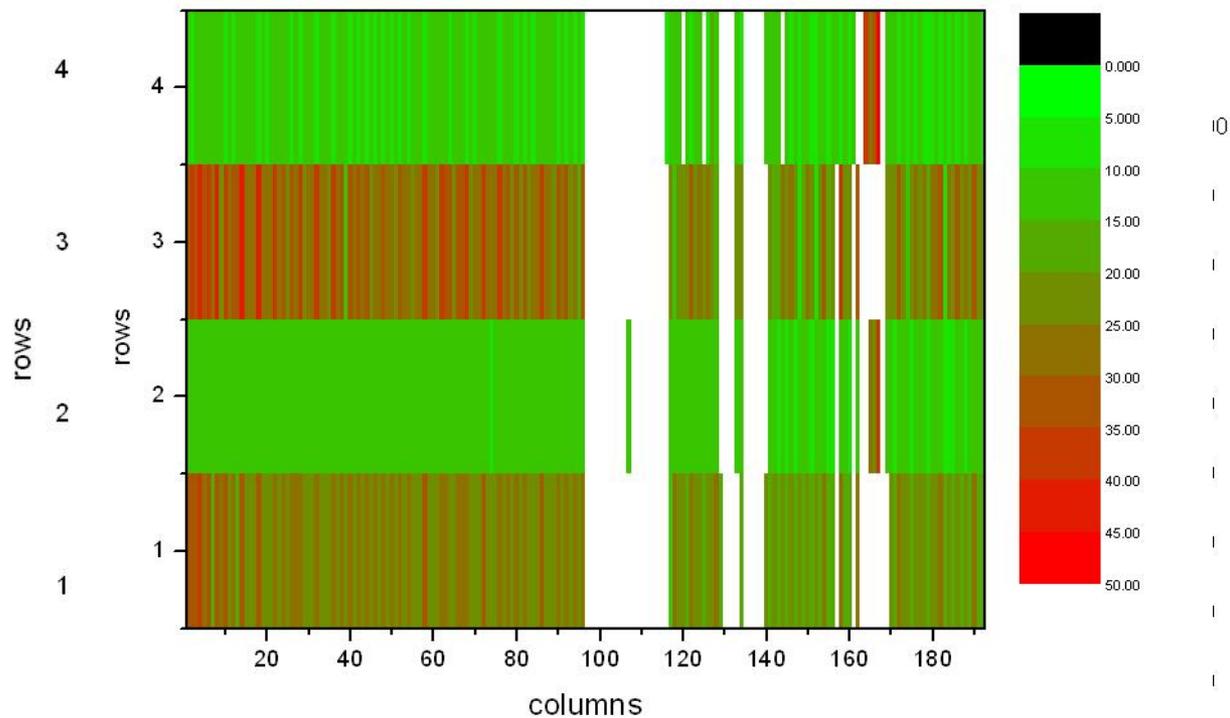
Sheet resistance 300Ohm/sq.
(3x lower than in the old technology due
to better implant activation)

Estimation: @ $I_d=80\mu A$, $g_m=50\mu S$

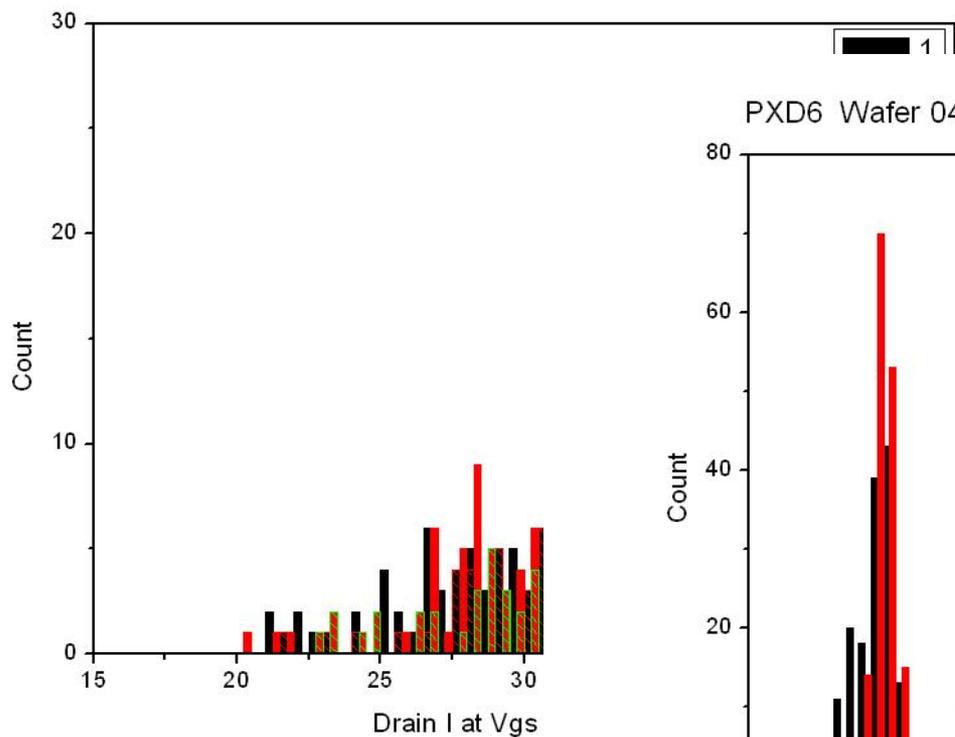
-> $\Delta I \approx 4\mu A$

We will see an odd-even behavior
but no change with radiation

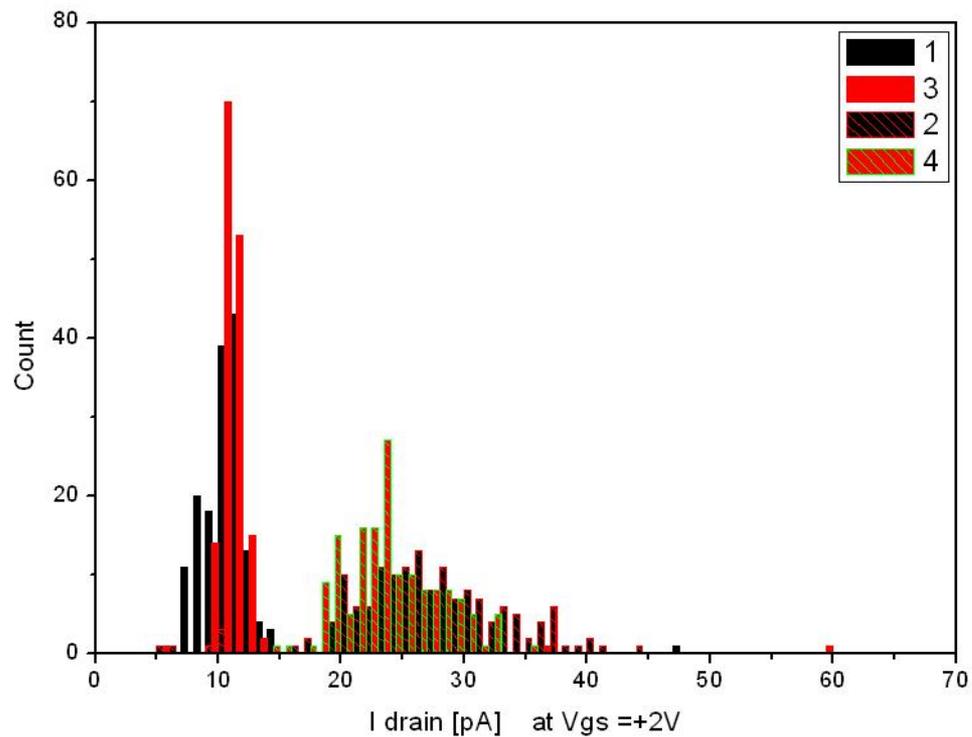
PXD6 Wafer 04 I00 1Gate 1 SW Id @ Vgs= +2V OFF state [pA]



PXD6 Wafer 04 I00 1st Gate 1st SW ON state rows



PXD6 Wafer 04 I00 1st Gate 1st SW OFF state rows



W04 I00 SW4 Gate 1

